

ABSTRACT OF THE DISCLOSURE

According to the package board of the present invention,
each soldering pad formed on the top surface of the package board,
5 on which an IC chip is to be mounted, is small (133 to 170 μ m
in diameter), so the metallic portion occupied by the soldering
pads on the surface of the package board is also small. On the
other hand, each soldering pad formed on the bottom surface of
the package board, on which a mother board, etc. are to be
10 mounted, is large (600 μ m in diameter), so the metallic portion
occupied by the soldering pads on the surface of the package
board is also large. Consequently, a dummy pattern 58M is
formed between conductor circuits 58U and 58U for forming signal
lines on the IC chip side surface of the package board thereby
15 to increase the metallic portion on the surface and adjust the
rate of the metallic portion between the IC chip side and the
mother board side of the package board, protecting the package
board from warping in the manufacturing processes, as well as
during operation.

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